















5. Heats rapidly resulting in thermal shock to materials.
6. Solder balling from vaporization of flux can occur
7. Optics must be cleaned regularly

Hot Air Heating:

1. Upper temperature limit is above degradation temperature of materials
2. Strict limits on the position and shape of the flowing air column must be maintained
3. Nearby components may need to be protected
4. Potential for thermal shock depending on geometries and material properties

Total Reflow Heating:

1. Additional thermal excursion above soldering temperatures
2. Thermal mass necessitates an increase in reflow temperatures
3. Additional processing steps necessary
4. Not always applicable because of components on assembled PWBs